64K (8K x 8)

**CMOS** 

E<sup>2</sup>PROM

WWW.DZSC.COM

#### **Features**

- Fast Read Access Time 120 ns
- Fast Byte Write 200 μs or 1 ms
- Self-Timed Byte Write Cycle Internal Address and Data Latches Internal Control Timer

**Automatic Clear Before Write** 

 Direct Microprocessor Control READY/BUSY Open Drain Output DATA Polling

Low Power

30 mA Active Current 100 μA CMOS Standby Current

High Reliability

Endurance: 10<sup>4</sup> or 10<sup>5</sup> Cycles
Data Retention: 10 Years

5V ± 10% Supply

CMOS and TTL Compatible Inputs and Outputs

• JEDEC Approved Byte-Wide Pinout

Commercial and Industrial Temperature Ranges

#### **Description**

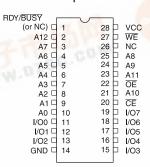
The AT28C64 is a low-power, high-performance 8,192 words by 8 bit nonvolatile Electrically Erasable and Programmable Read Only Memory with popular, easy to use features. The device is manufactured with Atmel's reliable nonvolatile technology.

(continued)

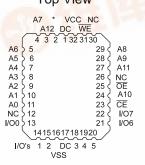
### **Pin Configurations**

Pin Name	Function
A0 - A12	Addresses
CE	Chip Enable
ŌE	Output Enable
WE	Write Enable
1/00 - 1/07	Data Inputs/Outputs
RDY/BUSY	Ready/Busy Output
NC	No Connect
DC	Don't Connect

PDIP, SOIC Top View



LCC, PLCC Top View



\* =  $RDY/\overline{BUSY}$  (or NC)

Note: PLCC package pins 1 and 17 are DON'T CONNECT.

TSOP Top View



<u>AIMEL</u>

0001G



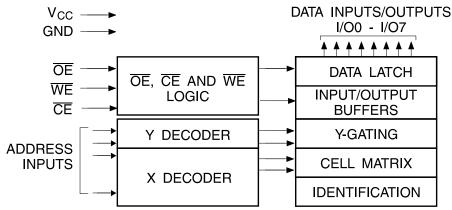
#### **Description** (Continued)

The AT28C64 is accessed like a Static RAM for the read or write cycles without the need for external components. During a byte write, the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of a write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. The device includes two methods for detecting the end of a write cycle, level detection of RDY/BUSY (unless pin 1 is N.C.) and DATA POLLING of I/O7. Once the end of a write cycle has been detected, a new access for a read or write can begin.

The CMOS technology offers fast access times of 120 ns at low power dissipation. When the chip is deselected the standby current is less than 100  $\mu$ A.

Atmel's 28C64 has additional features to ensure high quality and manufacturability. The device utilizes error correction internally for extended endurance and for improved data retention characteristics. An extra 32-bytes of E<sup>2</sup>PROM are available for device identification or tracking.

#### **Block Diagram**



#### **Absolute Maximum Ratings\***

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V
All Output Voltages with Respect to Ground0.6V to V <sub>CC</sub> + 0.6V
Voltage on OE and A9 with Respect to Ground

\*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **Device Operation**

**READ:** The AT28C64 is accessed like a Static RAM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in a high impedance state whenever CE or OE is high. This dual line control gives designers increased flexibility in preventing bus contention.

BYTE WRITE: Writing data into the AT28C64 is similar to writing into a Static RAM. A low pulse on the WE or CE input with OE high and CE or WE low (respectively) initiates a byte write. The address location is latched on the falling edge of WE (or CE); the new data is latched on the rising edge. Internally, the device performs a self-clear before write. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of two, a read operation will effectively be a polling operation.

**FAST BYTE WRITE:** The AT28C64E offers a byte write time of 200  $\mu$ s maximum. This feature allows the entire device to be rewritten in 1.6 seconds.

**READY/BUSY**: Pin 1 is an open drain READY/BUSY output that can be used to detect the end of a write cycle. RDY/BUSY is actively pulled low during the write cycle and is released at the completion of the write. The open drain connection allows for OR-tying of several devices to the same RDY/BUSY line. Pin 1 is not connected for the AT28C64X.

DATA POLLING: The AT28C64 provides DATA POLL-ING to signal the completion of a write cycle. During a write cycle, an attempted read of the data being written results in the complement of that data for I/O<sub>7</sub> (the other outputs are indeterminate). When the write cycle is finished, true data appears on all outputs.

WRITE PROTECTION: Inadvertent writes to the device are protected against in the following ways. (a) V<sub>CC</sub> sense— if V<sub>CC</sub> is below 3.8V (typical) the write function is inhibited. (b) V<sub>CC</sub> power on delay— once V<sub>CC</sub> has reached 3.8V the device will automatically time out 5 ms (typical) before allowing a byte write. (c) Write Inhibit—holding any one of OE low, CE high or WE high inhibits byte write cycles.

**CHIP CLEAR:** The contents of the entire memory of the AT28C64 may be set to the high state by the CHIP CLEAR operation. By setting CE low and OE to 12 volts, the chip is cleared when a 10 msec low pulse is applied to WE.

**DEVICE IDENTIFICATION:** An extra 32-bytes of  $E^2PROM$  memory are available to the user for device identification. By raising A9 to  $12 \pm 0.5V$  and using address locations 1FE0H to 1FFFH the additional bytes may be written to or read from in the same manner as the regular memory array.





### **DC and AC Operating Range**

		AT28C64-12	AT28C64-15	AT28C64-20	AT28C64-25
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
Vcc Power Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%

### **Operating Modes**

Mode	CE	ŌĒ	WE	I/O	
Read	VIL	VIL	VIH	Dout	
Write (2)	V <sub>I</sub> L	VIH	V <sub>I</sub> L	D <sub>IN</sub>	
Standby/Write Inhibit	VIH	X <sup>(1)</sup>	X	High Z	
Write Inhibit	X	Χ	VIH		
Write Inhibit	X	VIL	X		
Output Disable	Χ	Vih	X	High Z	
Chip Erase	VIL	V <sub>H</sub> <sup>(3)</sup>	VIL	High Z	

Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .

#### **DC Characteristics**

Symbol	Parameter	Condition		Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V$ to $V_{CC} + 1V$			10	μΑ
ILO	Output Leakage Current	$V_{I/O} = 0V$ to $V_{CC}$			10	μΑ
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current CMOS	$\overline{\text{CE}}$ = V <sub>CC</sub> - 0.3V to V <sub>CC</sub> + 1.0V			100	μΑ
lone	V <sub>CC</sub> Standby Current TTL	$\overline{\text{CE}}$ = 2.0V to V <sub>CC</sub> + 1.0V	Com.		2	mA
I <sub>SB2</sub>	VCC Standby Current TTL	CE = 2.00  to  VCC + 1.00	Ind.		3	mA
loo	Vcc Active Current AC	<u>f = </u> 5 MHz; I <sub>OUT</sub> = 0 mA	Com.		30	mA
Icc	VCC Active Current AC	CE = V <sub>IL</sub>	Ind.		45	mA
VIL	Input Low Voltage				0.8	V
VIH	Input High Voltage			2.0		V
VoL	Output Low Voltage	I <sub>OL</sub> = 2.1 mA = 4.0 mA for RDY/BUSY			.45	V
Vон	Output High Voltage	Ι <sub>ΟΗ</sub> = -400 μΑ		2.4		V

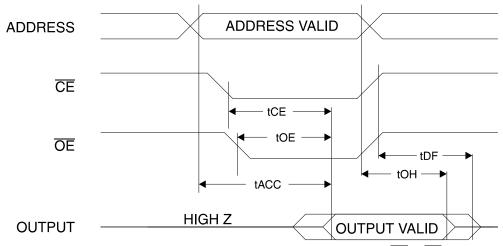
<sup>2.</sup> Refer to AC Programming Waveforms.

<sup>3.</sup>  $V_H = 12.0V \pm 0.5V$ .

#### **AC Read Characteristics**

		AT28C64-12		AT28	C64-15	AT28	C64-20	AT28	C64-25	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Min	Max	Units
tACC	Address to Output Delay		120		150		200		250	ns
tce (1)	CE to Output Delay		120		150		200		250	ns
toE (2)	OE to Output Delay	10	60	10	70	10	80	10	100	ns
t <sub>DF</sub> (3, 4)	CE or OE High to Output Float	0	45	0	50	0	55	0	60	ns
ton	Output Hold from OE, CE or Address, whichever occurred first	0		0		0		0		ns

## AC Read Waveforms (1, 2, 3, 4)



Notes: 1.  $\overline{\text{CE}}$  may be delayed up to  $t_{ACC}$  -  $t_{CE}$  after the address transition without impact on tACC.

- 2.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{CE}}$   $t_{\text{OE}}$  after the falling edge of CE without impact on tce or by tACC - toe after an address change without impact on tACC.
- 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first  $(C_L = 5 pF)$ .

OUTPUT

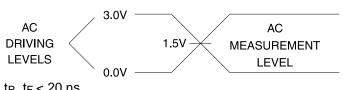
100 pF

**Output Test Load** 

5.0V

4. This parameter is characterized and is not 100% tested.

#### **Input Test Waveforms and Measurement Level**



Pin Capacitance (f = 1 MHz, T = 25°C) <sup>(1</sup>	i)
, , , ,	

	Тур	Max	Units	Conditions
CIN	4	6	pF	$V_{IN} = 0V$
Cout	8	12	pF	V <sub>OUT</sub> = 0V

Note: 1. This parameter is characterized and is not 100% tested.



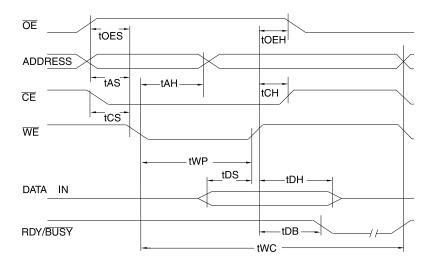


#### **AC Write Characteristics**

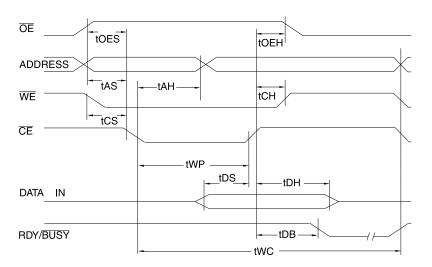
Symbol	Parameter		Min	Max	Units
tas, toes	Address, OE Set-up Time		10		ns
tah	Address Hold Time		50		ns
twp	Write Pulse Width (WE or CE)		100	1000	ns
t <sub>DS</sub>	Data Set-up Time		50		ns
tDH, tOEH	Data, OE Hold Time		10		ns
tcs, tch	$\overline{CE}$ to $\overline{WE}$ and $\overline{WE}$ to $\overline{CE}$ Set-up	and Hold Time	0		ns
t <sub>DB</sub>	Time to Device Busy			50	ns
Maita Cuala Tima		AT28C64		1.0	ms
twc	Write Cycle Time	AT28C64E		200	μs

#### **AC Write Waveforms**

#### **WE** Controlled



#### **CE** Controlled



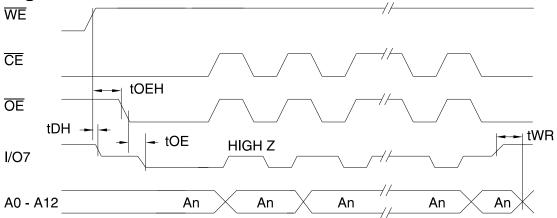
### **Data** Polling Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
tDH	Data Hold Time	10			ns
toeh	OE Hold Time	10			ns
toE	OE to Output Delay (2)				ns
t <sub>WR</sub>	Write Recovery Time	0			ns

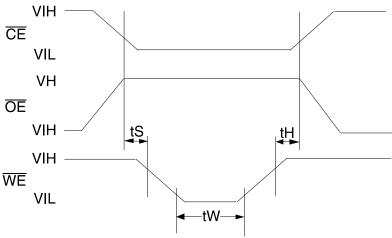
Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

### **Data Polling Waveforms**



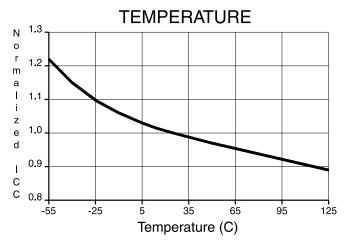
### **Chip Erase Waveforms**



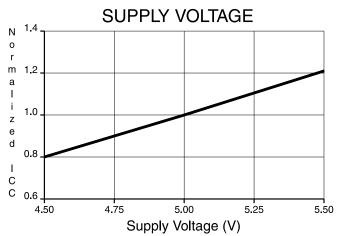
 $t_S = t_H = 1 \; \mu sec \; (min.)$   $t_W = 10 \; msec \; (min.)$   $V_H = 12.0V \pm 0.5V$ 

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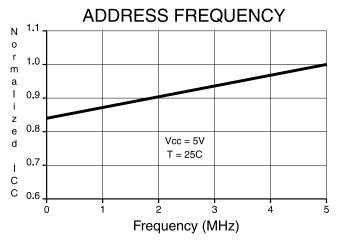
#### NORMALIZED SUPPLY CURRENT vs.



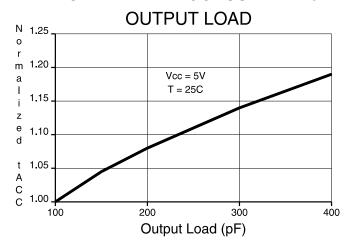
#### NORMALIZED SUPPLY CURRENT vs.



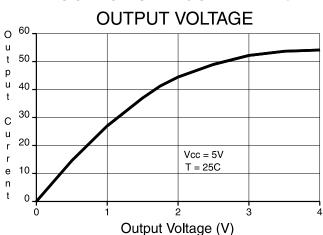
#### NORMALIZED SUPPLY CURRENT vs.



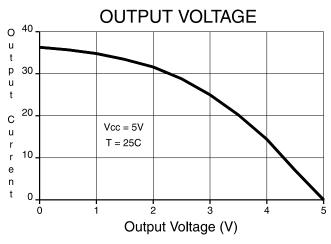
#### NORMALIZED ACCESS TIME vs.



### OUTPUT SINK CURRENT vs.



#### **OUTPUT SOURCE CURRENT vs.**



## Ordering Information (1)

tACC	Icc	(mA)	Ondonin v Oodo	Doolsons	On suction Dommo
(ns)	Active	Standby	Ordering Code	Package	Operation Range
120	30	0.1	AT28C64(E)-12JC AT28C64(E)-12PC AT28C64(E)-12SC AT28C64(E)-12TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64(E)-12JI AT28C64(E)-12PI AT28C64(E)-12SI AT28C64(E)-12TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
150	30	0.1	AT28C64(E)-15JC AT28C64(E)-15PC AT28C64(E)-15SC AT28C64(E)-15TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64(E)-15JI AT28C64(E)-15PI AT28C64(E)-15SI AT28C64(E)-15TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
200	30	0.1	AT28C64(E)-20JC AT28C64(E)-20PC AT28C64(E)-20SC AT28C64(E)-20TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64(E)-20JI AT28C64(E)-20PI AT28C64(E)-20SI AT28C64(E)-20TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
250	30	0.1	AT28C64(E)-25JC AT28C64(E)-25PC AT28C64(E)-25SC AT28C64(E)-25TC AT28C64-W	32J 28P6 28S 28T DIE	Commercial (0°C to 70°C)
	45	0.1	AT28C64(E)-25JI AT28C64(E)-25PI AT28C64(E)-25SI AT28C64(E)-25TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)

Note: 1. See Valid Part Number table below.



	Package Type				
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)				
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)				
28S	28 Lead, 0.300" Wide, Plastic Gull Wing, Small Outline (SOIC)				
28T	28 Lead, Plastic Thin Small Outline Package (TSOP)				
W	Die				
	Options				
Blank	Standard Device: Endurance = 10K Write Cycles; Write Time = 1 ms				
Е	High Endurance Option: Endurance = 100K Write Cycles; Write Time = 200 μs				

### **Ordering Information**

tACC	c Icc (mA)		On Lorino On Lo	Deed en	Omeration Berne
(ns)	Active	Standby	Ordering Code	Package	Operation Range
150	30	0.1	AT28C64X-15JC AT28C64X-15PC AT28C64X-15SC AT28C64X-15TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64X-15JI AT28C64X-15PI AT28C64X-15SI AT28C64X-15TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
200	30	0.1	AT28C64X-20JC AT28C64X-20PC AT28C64X-20SC AT28C64X-20TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64X-20JI AT28C64X-20PI AT28C64X-20SI AT28C64X-20TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
250	30	0.1	AT28C64X-25JC AT28C64X-25PC AT28C64X-25SC AT28C64X-25TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64X-25JI AT28C64X-25PI AT28C64X-25SI AT28C64X-25TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)

#### **Valid Part Numbers**

The following table lists standard Atmel products that can be ordered.

Device Numbers	Speed	Package and Temperature Combinations
AT28C64 X	12	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	15	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	20	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	25	JC, JI, PC, PI, SC, SI, TC, TI

Package Type				
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28 Lead, 0.600" Wide Plastic Dual Inline Package (PDIP)			
28S	28 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)			
28T	28 Lead, Plastic Thin Small Outline Package (TSOP)			

